

# Silicon Carbide (SiC) MOSFET - EliteSiC, 65 mohm, 1200 V, M3S, D2PAK-7L NVBG070N120M3S

#### **Features**

- Typ.  $R_{DS(on)} = 65 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge  $(Q_{G(tot)} = 57 \text{ nC})$
- High Speed Switching with Low Capacitance ( $C_{oss} = 57 \text{ pF}$ )
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

#### **Typical Applications**

- Automotive On Board Charger
- Automotive DC/DC Converter for EV/HEV

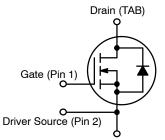
#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	1200	V
Gate-to-Source Voltage			$V_{GS}$	-10/+22	V
Recommended Operation Values of Gate-to-Source Voltage		$V_{GSop}$	-3/+18	V	
Continuous Drain Current (Notes 2, 3)	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	36	Α
Power Dissipation (Note 2)			P <sub>D</sub>	172	W
Continuous Drain Current (Notes 2, 3)	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	25	Α
Power Dissipation (Note 2)			P <sub>D</sub>	86	W
Pulsed Drain Current (Note 4)	T <sub>C</sub> = 25°C		I <sub>DM</sub>	93	Α
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode) T <sub>C</sub> = 25°C, V <sub>GS</sub> = -3 V (Note 2)			I <sub>S</sub>	33	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 13.5 A, L = 1 mH) (Note 5)			E <sub>AS</sub>	91	mJ
Maximum Temperature for Soldering (10 s)			TL	270	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface mounted on a FR-4 board using1 in<sup>2</sup> pad of 2 oz copper.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. The maximum current rating is based on typical RDS(on) performance.
- 4. Repetitive rating, limited by max junction temperature.
- 5.  $E_{AS}$  of 91 mJ is based on starting  $T_J$  = 25°C;  $\dot{L}$  = 1 mH,  $I_{AS}$  = 13.5 A,  $V_{DD}$  = 100 V,  $V_{GS}$  = 18 V.

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
1200 V	87 m $\Omega$ @ 18 V	36 A



Power Source (Pins 3, 4, 5, 6, 7)

#### **N-CHANNEL MOSFET**



D2PAK-7L CASE 418BJ

#### **MARKING DIAGRAM**

BG070N 120M3S AYWWZZ

BG070N120M3S = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NVBG070N120M3S	D2PAK-7L	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 2)	$R_{ heta JC}$	0.87	°C/W
Junction-to-Ambient - Steady State (Notes 1, 2)	$R_{ heta JA}$	40	

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF-STATE CHARACTERISTICS	•			1		
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	1200	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 1 mA, referenced to 25°C (Note 7)	-	0.3	-	V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 1200 V	-	-	100	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = +22/-10 V, V <sub>DS</sub> = 0 V	-	-	±1	μА
ON-STATE CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 7 \text{ mA}$	2.04	2.9	4.4	V
Recommended Gate Voltage	V <sub>GOP</sub>		-3	-	+18	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 18 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 25°C	-	65	87	mΩ
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175°C (Note 7)	-	136	-	
Forward Transconductance	9FS	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 15 A (Note 7)	-	12	_	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE			•	•	
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 800 V	-	1230	_	pF
Output Capacitance	C <sub>OSS</sub>		-	57	_	
Reverse Transfer Capacitance	C <sub>RSS</sub>		-	5	_	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -3/18 \text{ V}, V_{DS} = 800 \text{ V},$ $I_{D} = 15 \text{ A}$	-	57	_	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	I <sub>D</sub> = 15 A	-	3.2	_	1
Gate-to-Source Charge	$Q_{GS}$		-	9.6	_	
Gate-to-Drain Charge	$Q_{GD}$		-	17	_	
Gate-Resistance	$R_{G}$	f = 1 MHz	-	4.2	-	Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS} = -3/18 \text{ V},$	-	11	_	ns
Rise Time	t <sub>r</sub>	V <sub>DS</sub> = 800 V, I <sub>D</sub> = 15 A,	-	12	_	
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$R_G = 4.7 \Omega$ inductive load (Notes 6, 7)	-	30	_	
Fall Time	t <sub>f</sub>		-	8.8	_	
Turn-On Switching Loss	E <sub>ON</sub>		-	119	-	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>		-	36	-	
Total Switching Loss	E <sub>tot</sub>		-	155	_	
SOURCE-DRAIN DIODE CHARACTERISTICS						
Continuous Source-Drain Diode Forward Current (Note 2)	I <sub>SD</sub>	$V_{GS} = -3 \text{ V, T}_{C} = 25^{\circ}\text{C}$ (Note 7)	-	-	33	Α
Pulsed Source–Drain Diode Forward Current (Note 4)	I <sub>SDM</sub>		-	-	93	
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = -3 V, I <sub>SD</sub> = 15 A, T <sub>J</sub> = 25°C	-	4.7	_	V

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified) (continued)

,	o .	1 / ( /				
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
SOURCE-DRAIN DIODE CHARACTERIST	rics					
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -3/18 \text{ V}, I_{SD} = 15 \text{ A},$ $dI_S/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 800 \text{ V}$	-	15	-	ns
Reverse Recovery Charge	$Q_{RR}$	- αι <sub>S</sub> /ατ = 1000 Α/μs, ν <sub>DS</sub> = 800 ν (Note 7)	-	63	-	nC
Reverse Recovery Energy	E <sub>REC</sub>	1	-	5.7	-	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>	1	-	8.6	-	Α
Charge time	t <sub>A</sub>		-	8.3	-	ns
Discharge time	t <sub>B</sub>	1	-	6.3	-	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. E<sub>ON</sub>/E<sub>OFF</sub> result is with body diode

7. Defined by design, not subject to production test.

#### **TYPICAL CHARACTERISTICS**

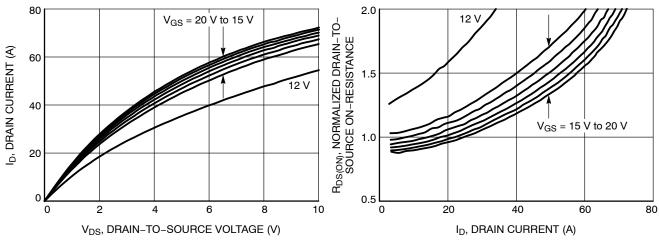


Figure 1. On-Region Characteristics

Figure 2. Normalized On–Resistance vs. Drain Current and Gate Voltage

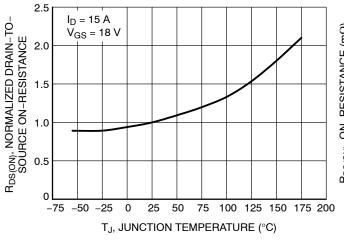


Figure 3. On–Resistance Variation with Temperature

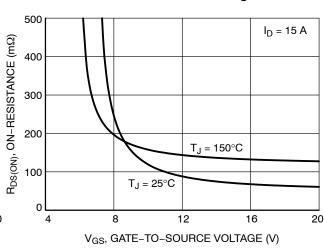


Figure 4. On-Resistance vs. Gate-to-Source Voltage

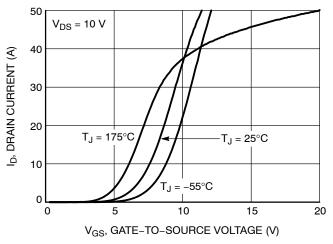


Figure 5. Transfer Characteristics

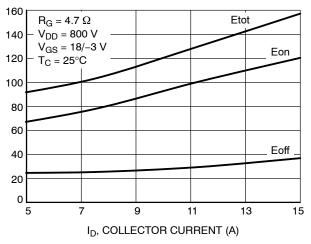


Figure 6. Switching Loss vs. Collector Current

SWITCHING LOSS (µJ)

#### **TYPICAL CHARACTERISTICS**

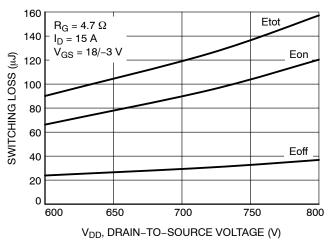


Figure 7. Switching Loss vs. Drain-to-Source Voltage

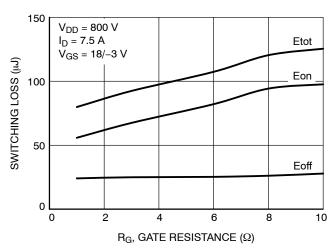


Figure 8. Switching Loss vs. Gate Resistance

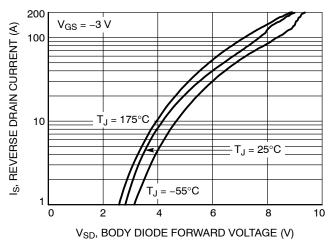


Figure 9. Reverse Drain Current vs. Body Diode Forward Voltage

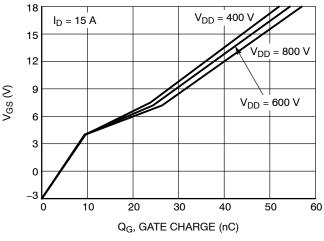


Figure 10. Gate-to-Source Voltage vs. Total Charge

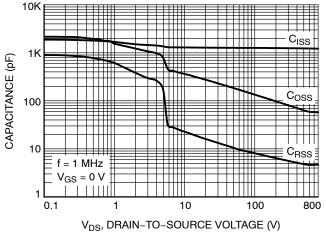


Figure 11. Capacitance vs. Drain-to-Source Voltage

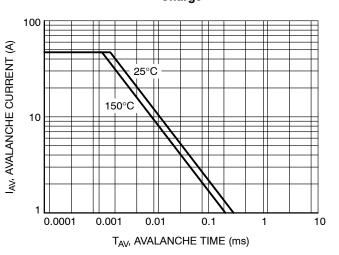


Figure 12. Unclamped Inductive Switching Capability

#### **TYPICAL CHARACTERISTICS**

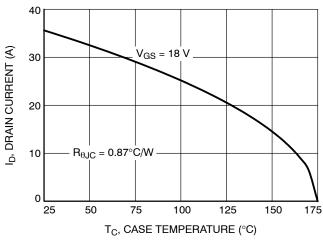


Figure 13. Maximum Continuous Drain Current vs. Case Temperature

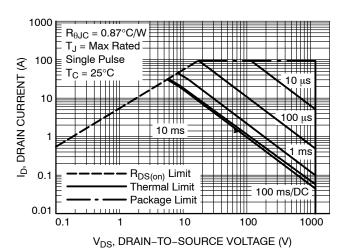


Figure 14. Safe Operating Area

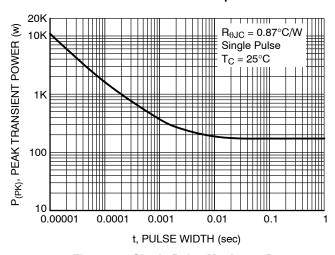


Figure 15. Single Pulse Maximum Power Dissipation

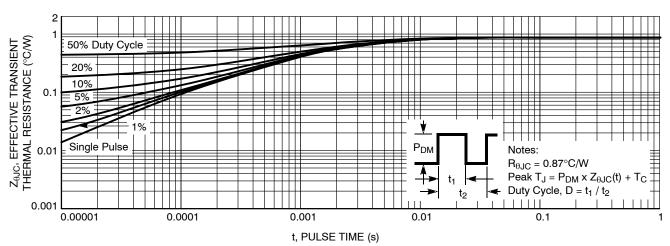
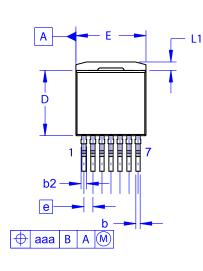
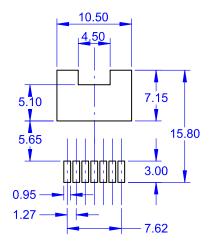


Figure 16. Junction-to-Case Transient Thermal Response

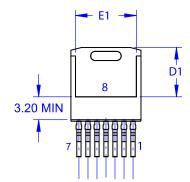
#### **PACKAGE DIMENSIONS**

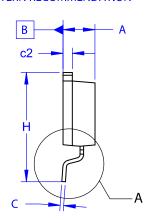
### D<sup>2</sup>PAK7 (TO-263-7L HV) CASE 418BJ **ISSUE B**





LAND PATTERN RECOMMENDATION





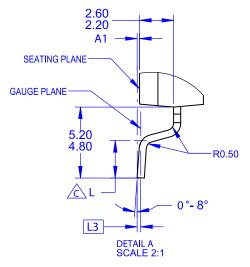
#### NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.
- OUT OF JEDEC STANDARD VALUE.

  D. DIMENSION AND TOLERANCE AS PER ASME
  Y14.5-2009.

  E. DIMENSIONS ARE EXCLUSIVE OF BURRS,
  MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	4.30	4.50	4.70			
<b>A</b> 1	0.00	0.10	0.20			
b2	0.60	0.70	0.80			
b	0.51	0.60	0.70			
С	0.40	0.50	0.60			
c2	1.20	1.30	1.40			
D	9.00	9.20	9.40			
D1	6.15	6.80	7.15			
Е	9.70	9.90	10.20			
E1	7.15	7.65	8.15			
е	~	1.27	~			
Н	15.10	15.40	15.70			
L	2.44	2.64	2.84			
L1	1.00	1.20	1.40			
L3	~	0.25	~			
aaa	~	~	0.25			



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C3M0045065K E3M0120090J C3M0065090J-TR C3M0120100J C3M0075120J DMWS120H100SM4 DMWSH120H28SM4
DMWSH120H90SM4 DMWSH120H90SM4Q DMWSH120H28SM4Q DMWSH120H90SCT7Q DMWSH120H28SM3
DMWSH120H43SM3 DMWSH120H90SM3 DMWSH120H28SM3Q DMWSH120H90SM3Q DIF120SIC053-AQ DIW120SIC059-AQ
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G3R20MT12K G3R20MT12N G3R20MT17K G3R20MT17N G3R30MT12J-TR G3R30MT12K G3R350MT12D G3R40MT12D
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